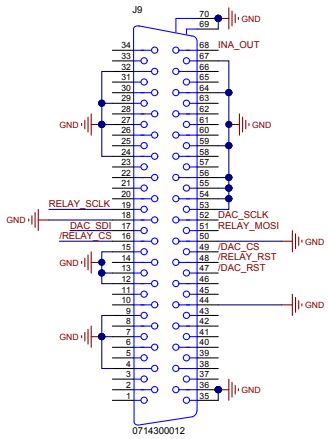
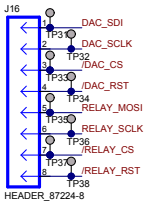


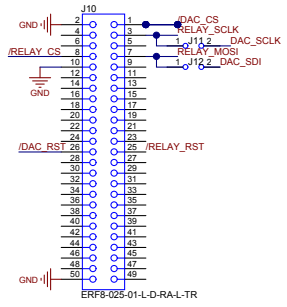
Connector for PIXe 6289



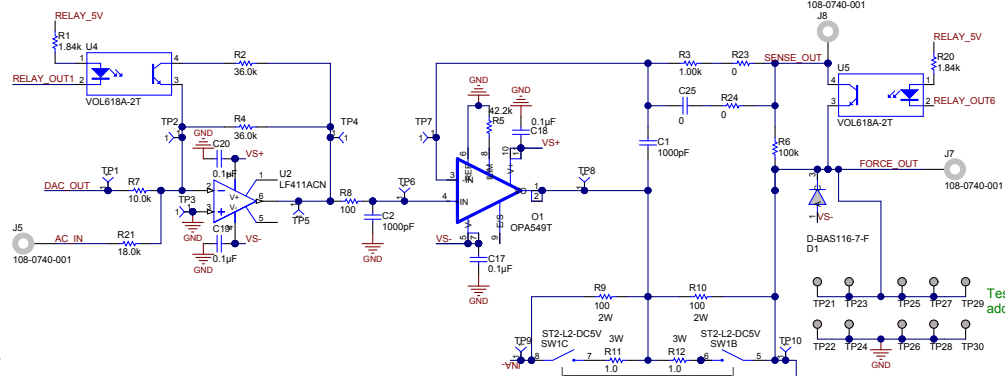
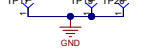
100 mil Header



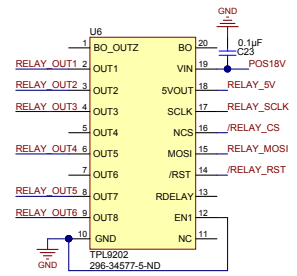
SDCC Connector



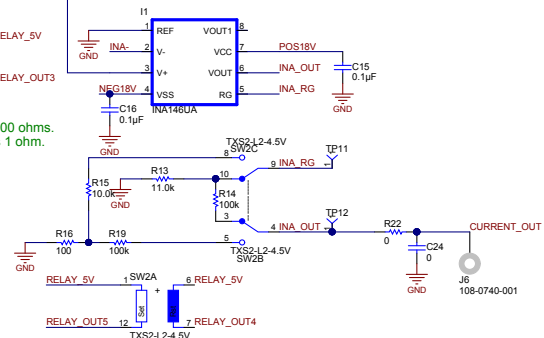
All test points are TP-040_RND



Test points allow for a load resistance to be easily added to the circuit.



SW1A controls relays SW1B and SW1C. At open (rst) position, shunt resistance is 100 ohms. At closed (set) position, shunt resistance is 1 ohm.



SW2A controls relays SW2B and SW2C. At default (rst) position the INA gain is 1 V/V. At set position the INA gain is 100 V/V.

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Number: T10U001	Rev: 2	Designed for: Public Release	Mod. Date: 8/14/2013
S/N Rev: Not in version control		Project Title: 30V @ 1A Power Supply	
Drawn By: Adam Rozenberga		Sheet Title: Power Supply Schematic	
Engineer: Adam Rozenberga		Assembly Variant: Variant name not interpreted	
		File: PowerSupply_Sch1.Doc	
		Sheet 1 of 1	
		Contact: http://www.ti.com/support	
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